

ABSTRACT

A method, for evaluating a photocurable adhesive used in a dicing/die bonding integrated film, includes a step in which a photocurable adhesive sheet composed of a photocurable adhesive is prepared, a tensile test is performed to create a graph of a test force regarding displacement, and an area surrounded by a hysteresis curve is obtained as loss work from the hysteresis curve, a step in which a dicing/die bonding integrated film including a photocurable adhesive layer composed of a photocurable adhesive is prepared, the photocurable adhesive layer is irradiated with ultraviolet rays to form a cured product of the photocurable adhesive layer, and a peeling force when a bonding adhesive layer and the cured product of the photocurable adhesive layer are peeled apart is measured, and a step in which quality of the photocurable adhesive is determined on the basis of the loss work and the peeling force.

No Suitable Figure